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(71) Applicant: **APPLIED MATERIALS, INC.** [US/US]; 3050 Bowers Avenue, Santa Clara, California 95054 (US).

(72) Inventors: **GAUTAM, Ribhu**; c/o Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US). **LAU, Shu-Kwan**; c/o Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US). **ISHII, Masato**; c/o Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US). **CHEN, Miao-Chun**; c/o Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US). **SHEN, Kuan Chien**; c/o Applied Materials, Inc., Law Dept., M/S 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US).

(74) Agent: **PATTERSON, B. Todd** et al.; PATTERSON + SHERIDAN LLP, 24 Greenway Plaza, Suite 1600, Houston, Texas 77046 (US).

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(54) Title: SUSCEPTOR TRANSFER FOR PROCESS CHAMBER

(57) Abstract: A method of moving a susceptor in a processing system, suitable for use in semiconductor processing, is provided. The method includes: moving a first susceptor from an interior volume of a first enclosure to an interior volume of a process chamber during a first time period; and positioning, during a second time period, a first substrate on the first susceptor when the first susceptor is in the process chamber, wherein the interior volume of the first enclosure and interior volume of the process chamber are maintained at a non-atmospheric pressure from the beginning of the first time period until the end of the second time period.

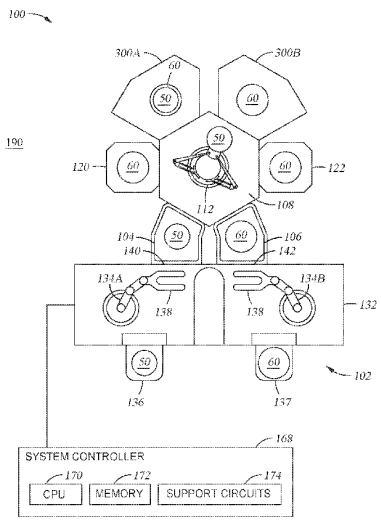


Fig. 1

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